個人簡介

Dr. Ho-Ming Tong
(唐和明)

- 覆晶/扇出/扇入晶圓級封裝、2.5D IC、3D IC、嵌入式系統級封裝和光電子封裝的先驅
  - IEEE (國際電氣與電子工程師學會) - 尖端IC集成電路技術院士
  - 中華民國科技管理學會院士
  - 電子製造技術獎 - IEEE CPMT (Component, Packaging and Manufacturing Technology)
  - John A. Wagnon卓越技術貢獻獎 - iMAPS (國際微電子暨構裝學會)
  - 傑出研究獎-潘文淵文教基金會
  - IBM Watson 研究中心總部獎
  - IBM大師級發明家獎 (IBM Master Inventor)
  - IBM高階人才庫成員 (IBM Executive pool)…

- 銓心半導體(現職) - 共同創辦人暨研發長
- 杰群電子 (5年) - 首席執行長兼總裁
- 台達電子 (2年) - 零組件事業部/乾坤科技總經理
- 日月光集團 (14年) - 首席研發長暨集團研發總經理
- 福懋科技 (2年半) - 創始團隊執行副總
- IBM, J. Watson Research Center (9年) - Research Staff Member (科研專家)
- IBM, Fishkill Facility (5年) - 資深工程經理
- SEMI 國際半導體協會 - 前董事會成員
- 美國哥倫比亞大學博士(Ph.D.)暨雙碩士; 台灣大學化工學士
- 擁有110項以上的專利，超過110篇技術論文和7本書/特刊

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Profile

Dr. Ho-Ming Tong
(唐和明)

- Pioneer in flip chip, fanout/fan-in wafer-level packaging, 2.5D IC, 3D IC, embedded SiPs & photonics packaging
  - IEEE Fellow for Leadership in Leading-edge Integrated Circuits Technology
  - Fellow, the Chinese Society for Management of Technology, Taiwan, ROC
  - The Electronics Manufacturing Technology Award, IEEE CPMT
  - The John A. Wagnon Technical Achievements Award from imps
  - The Outstanding Research Award of Pan Wen Yuan Foundation
  - IBM Watson Research Headquarters Award, IBM Executive Pool and IBM Master Inventor…
- Co-founder and Chief R&D Officer, nD-HI Technologies Lab (present)
- CEO & President, Great Team Backend Foundry (5+ years)
- President, Cyntec/Delta Components Business Group (2 years)
- Chief R&D Officer & GM of Group R&D, ASE Group (14 years)
- Founding EVP, Formosa Advanced Technologies (2+ years)
- Research Staff Member, IBM Thomas J. Watson Research Center (9 years)
- Senior Engineering Manager, IBM East Fishkill Facility (5 years)…
- Ex-board member, SEMI International
- Ph.D., M.S., and M. Ph., Columbia University; B.S., Chem. E., National Taiwan University
- 110+ patents, 110+ technical papers and 7 books/special journal issues

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